



FDC608PZ

P-Channel 2.5V Specified PowerTrench® MOSFET

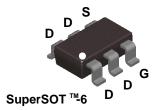
General Description

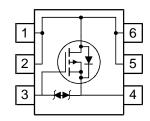
This P-Channel 2.5V specified MOSFET is produced using Fairchild Semiconductor's advanced PowerTrench process that has been especially tailored to minimize the on-state resistance and yet maintain low gate charge for superior switching performance.

These devices are well suited for battery power applications: load switching and power management, battery power circuits, and DC/DC conversions.

Features

- -5.8 A, -20 V. $R_{DS(ON)} = 30 \ m\Omega \ @ \ V_{GS} = -4.5 \ V$ $R_{DS(ON)} = 43 \ m\Omega \ @ \ V_{GS} = -2.5 \ V$
- · Low Gate Charge
- High performance trench technology for extremely low Research.
- SuperSOT [™] –6 package: small footprint (72% smaller than standard SO–8) low profile (1mm thick).





Absolute Maximum Ratings T_A=25°C unless otherwise noted

	<u> </u>			
Symbol	Parameter		Ratings	Units
V _{DSS}	Drain-Source Voltage		-20	V
V _{GSS}	Gate-Source Voltage		±12	V
I _D	Drain Current - Continuous	(Note 1a)	-5.8	А
	- Pulsed		-20	
P _D	Maximum Power Dissipation	(Note 1a)	1.6	W
		(Note 1b)	0.8	
T_J, T_{STG}	Operating and Storage Junction Temperature Range		-55 to +150	°C

Thermal Characteristics

$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1a)	78	°C/W
Raic	Thermal Resistance, Junction-to-Case	(Note 1)	30	°C/W

Package Marking and Ordering Information

Device Marking	Device	Reel Size	Tape width	Quantity
.608Z	FDC608PZ	7"	8mm	3000 units

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Char	acteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	-20			V
ΔBV _{DSS} ΔT _J	Breakdown Voltage Temperature Coefficient	$I_D = -250 \mu A$, Referenced to 25°C		-10		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -16 \text{ V}, V_{GS} = 0 \text{ V}$			-1	μА
I _{GSS}	Gate-Body Leakage	$V_{GS} = \pm 12 \text{ V}, V_{DS} = 0 \text{ V}$			±10	μΑ
On Char	acteristics (Note 2)					
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	-0.4	-1.0	-1.5	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate Threshold Voltage Temperature Coefficient	$I_D = -250 \mu A$, Referenced to 25°C		3		mV/°C
R _{DS(on)}	Static Drain–Source On–Resistance	$\begin{tabular}{lllllllllllllllllllllllllllllllllll$		26 38 35	30 43	mΩ
$I_{D(on)}$	On-State Drain Current	$V_{GS} = -4.5 \text{ V}, \qquad V_{DS} = -5 \text{ V}$	-20			Α
g _{FS}	Forward Transconductance	$V_{DS} = -10 \text{ V}, \qquad I_{D} = -5.8 \text{ A}$		22		S
Dynamic	Characteristics					
C _{iss}	Input Capacitance	$V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V},$		1330		pF
C _{oss}	Output Capacitance	f = 1.0 MHz		270		pF
C _{rss}	Reverse Transfer Capacitance			230		pF
R _G	Gate Resistance	$V_{GS} = 15 \text{ mV}, f = 1.0 \text{ MHz}$		12		Ω
Switchin	g Characteristics (Note 2)					
t _{d(on)}	Turn-On Delay Time	$V_{DD} = -10 \text{ V}, \qquad I_{D} = -1 \text{ A},$		13	24	ns
t _r	Turn-On Rise Time	$V_{GS} = -4.5 \text{ V}, \qquad R_{GEN} = 6 \Omega$		8	16	ns
t _{d(off)}	Turn-Off Delay Time	7		91	145	ns
t _f	Turn-Off Fall Time	7		60	96	ns
Q _g	Total Gate Charge	$V_{DS} = -10 \text{ V}, \qquad I_{D} = -5.8 \text{ A},$		17	23	nC
Q _{gs}	Gate-Source Charge	$V_{GS} = -4.5 \text{ V}$		3		nC
Q _{gd}	Gate-Drain Charge			6		nC
Drain-Se	ource Diode Characteristics	and Maximum Ratings				
Is	Maximum Continuous Drain-Source				-1.3	Α
V _{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = -1.3 \text{ A} \text{(Note 2)}$		-0.7	-1.2	V
t _{rr}	Diode Reverse Recovery Time	$I_F = -5.8 \text{ A}, d_{iF}/d_t = 100 \text{A}/\mu \text{s}$		40	60	ns
Q _{rr}	Diode Reverse Recovery Charge	$I_F = -5.8 \text{ A}, d_{iF}/d_t = 100 \text{A/} \mu \text{s}$		15	23	nC

Notes

- 1. $R_{\theta,JA}$ is the sum of the junction-to-case and case-to-ambient resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta,JC}$ is guaranteed by design while $R_{\theta,CA}$ is determined by the user's board design.
 - a. 78°C/W when mounted on a 1in^2 pad of 2oz copper on FR-4 board.
 - b. 156°C/W when mounted on a minimum pad.
- 2. Pulse Test: Pulse Width $\leq 300~\mu s,~Duty~Cycle \leq 2.0\%$

Typical Characteristics

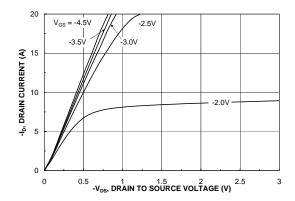


Figure 1. On-Region Characteristics.

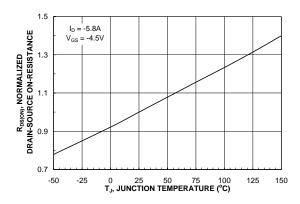


Figure 3. On-Resistance Variation with Temperature.

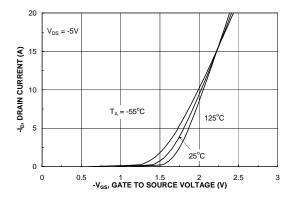


Figure 5. Transfer Characteristics.

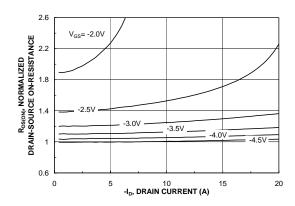


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

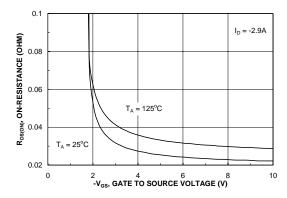


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

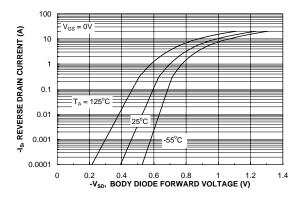
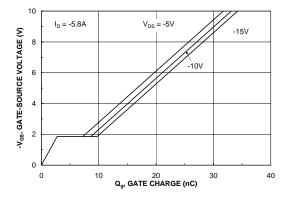


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Characteristics



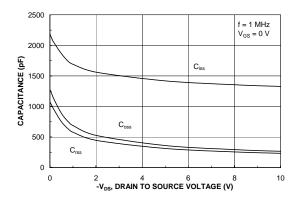
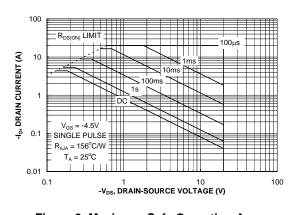


Figure 7. Gate Charge Characteristics.





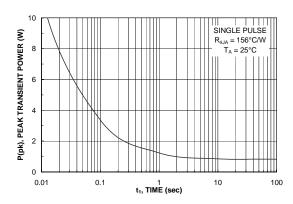


Figure 9. Maximum Safe Operating Area.

Figure 10. Single Pulse Maximum Power Dissipation.

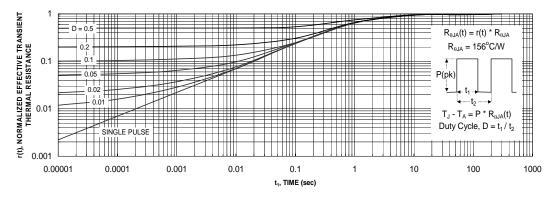


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1b. Transient thermal response will change depending on the circuit board design.

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